



APPENDICES

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APPENDIX A: OPERATING AGREEMENT WITH IES MAJORITY SPONSORED CONFERENCE ORGANIZERS

This Agreement is entered into by and between the Institute of Electrical and Electronics Engineers, Inc. (IEEE) Industrial Electronics Society (IES) and <General Chair name>, General Chair of the <Conference name> (hereafter referred to as the “Conference”). These parties will be known as the “Society” and the “General Chair” respectively. This Agreement is for the purpose of providing the terms and conditions that will govern the conduct of the “Conference”.

IT IS AGREED as follows:

1. The “Society” authorizes the “General Chair” to organize and conduct the “Conference” to be held <Conference dates>, in <Conference location>.
2. This Agreement (and any amendments thereto) shall be in force from the date of signing until the “Conference” is officially closed in accordance with applicable IEEE requirements, procedures, and policy.
3. The “Conference” will be planned and conducted according to the IES Conferences Policies and Guidelines, the IEEE Conference Manual, and the IEEE Bylaws, Policies and Procedures. Inconsistencies among these sources will be resolved in writing by the signatories to this Agreement.
4. The “General Chair” shall be responsible for the conduct of the conference in accordance with this Agreement.
5. The “General Chair” commits himself/herself to instruct all members of the “Conference” committees to strictly follow the IES Conferences Policies and Guidelines in their respective areas of responsibility and, if deemed necessary by the “Society”, to attend the first edition of IES POCO held after the signature of this Agreement.
6. The “Society” and the “General Chair” represents and warrants that:
 - (a) it has the right to enter into this Agreement;
 - (b) it has not taken and will not take, during the term of this Agreement, any action that would violate the rights of any party to this Agreement or any third party; and
 - (c) it has not taken and will not take, during the term of this Agreement, any action that would impair the full exercise by any party to this Agreement of all the rights granted herein.

7. The "Society" shall have authority to make representations or warranties for the other party or to otherwise bind the other party.
8. Any controversy, claim, dispute, or question arising in connection with this Agreement shall be determined and settled by arbitration in Piscataway, NJ before a single IEEE appointed arbitrator in accordance with the Bylaws of the IEEE.
9. This Agreement represents the entire agreement between the "Society" and the "General Chair" and it shall not be modified or amended except as agreed to in writing signed by both parties.
10. This Agreement shall be binding upon all parties hereto and upon their respective licensees, successors, and assigns.
11. If one of the parties to this Agreement waives a breach by another party of any covenant or condition of this Agreement, the waiving party shall not be deemed to have waived the breach of any other condition or covenant.

APPENDIX B: LISTS OF CURRENT TRACKS IN IECON, ISIE, AND ICIT

NOTE: In addition to the tracks listed below, it is possible to include specific ones in given editions of an IES conference to respond to some particular circumstances, for instance related to the city / region / country where the conference is held (e.g., to include an automotive electronics track in a conference held in a city where there is a car factory).

IECON

I. Energy

I.1 Power Systems

Energy transmission and distribution; large and small hydro generators; static VAR and harmonic compensations; FACTS; active and hybrid filtering; power quality devices; power management; grid interconnection; distributed power generation; smart grid technologies.

I.2 Power Electronics

Power electronic devices; Sic Mosfet & Sic JFET technologies; modulation techniques; integrated power electronics; high frequency links; soft switching techniques; power electronics for smart grid; EMI and EMC issues; active and passive devices for power electronics.

I.3 Electrical Machines & Drives

DC/DC & AC/DC converters electrical machines; special machines and actuators; multiphase motors; AC motor drives control and applications; electrical machine design and modeling; thermal, noise and vibration issues in electrical machines; reliability, testing and diagnostics, special application of machines and drives.

I.4 Transportation Electrification

Advances in electric and hybrid cars; more-electric ships and aircraft, rail systems, personal transport; the motive, power grid, electronic intelligence and control technologies that make them possible.

I.5 Renewable Energy

Wind, solar, and wave energy converters; nano, pico and micro-hydro power generators; integrated renewable systems; hybrid electric vehicles; fuel cells; advanced batteries; offshore underwater converters; energy harvesting.

I.6 Energy Storage Systems

Energy efficiency and storage; energy storage devices and systems; static and dynamic wireless power transfer (WPT) for EVs (compact, car, city-car, SUVs, plug-in HEV, bus, train, E-bike); WPT system and component design; WPT system monitoring; EMI/EMC and shielding methodologies.

II. Control, Mechatronics and Robotics

II.1 Mechatronics & Robotics

Mechatronics systems; robotics; autonomous mobile robots; telerobotics and teleoperation; humanoid robots; multi-robot systems; intelligent transportation; distributed collaborative systems; security & safety applications; human-robot interface; vision-based robots.

II.2 Control Theory & Applications

Advanced control techniques; nonlinear and adaptive control; optimal and robust control; motion control; fuzzy control; intelligent control; complex systems control; networked control systems; process control; filtering, estimation and identification techniques; multi-agent systems; industrial control applications.

II.3 Fault Diagnosis/Prognosis & Fault Tolerant Control

Model-based FDDP algorithms; data-driven FDDP algorithms; statistical signal processing techniques; health condition monitoring; information fusion for diagnostics and prognostics; re-configuration techniques; fault management and control; fault diagnosis, fault prognosis, fault-tolerant control systems and applications; fault-tolerant sensors.

II.4 Signal Processing & Artificial Intelligence

Computer vision; virtual reality systems; industrial vision; virtual instrumentation; image & sound processing; digital signal processing; remote sensing; multimedia applications; artificial neural networks; fuzzy logic; genetic algorithms; industrial applications.

II.5 Micro/Nanotechnology

Micro-sensors & micro-actuators; micro-nano technology; micro-electro-mechanical systems (MEMS); RF systems integration; integrated optics and related technologies; polymer electronics; nanotechnology; microfluidics; MOEMS; RF-MEMS.

III. Information Communications Technology

III.1 Communications for Industrial & Factory Automation

Building automation; factory automation and communications; flexible manufacturing systems; industrial agents, security & safety industrial applications; infrastructures for industrial informatics portable electronics; automation systems for industrial power distribution; industrial applications of internet technologies, multimedia, and wireless communications.

III.2 Cloud computing, big data & industrial informatics

Cloud computing; integrated systems and processes; distributed collaborative systems; conjoint data; data mining for complex data structures including trees, graphs, text and spatial-temporal data; conjoint data mining for mixed information types including image, video, web and text data; joint mining of structured; semi-structured and unstructured information; stream data mining; mining of workflow; process mining.

III.3 Industrial cyber-physical systems

Digitalization of industrial systems and processes; industrial cyber-physical systems (ICPS); industrial internet-of-things (IIOT); industrial internet-of-services (IoS); CPS in industry 4.0; CPS architectures and service; ICPS and humans in the loop; ICPS complex system engineering; ICPS system of systems; applications of CPS; CPS and cyber-security; CPS modeling and analysis; large scale ICPS infrastructures; CPS scalability and complexity management; CPS validation and verification; collaborative ICPS systems; ICPS education and training; ICPS ethics.

III.4 Embedded systems & Chips

DSP and FPGA technologies; microprocessor and FPGA based control; embedded systems; real-time distributed embedded systems; technologies for system design; electronic system on chip; lab-on-chip devices and technologies; design methodologies and electronic design automation (EDA) tools.

III.5 Industrial Electronics and Education

ICTs and laboratory sessions; remote e-learning; internet applications; education and social networks; education and smart devices; sustainable development ICT aspects; on-line courses.

ISIE

1. Power Systems and Smart Grids.

Power Systems, Transmission, Power Quality, Utility Applications, Smart Grids.

2. Electrical Machines and Industrial Drives.

AC/DC Motor Drives, Electrical Machines Design/Modelling, Thermal/Vibrations Issues.

3. Control Systems and Applications.

Control Systems, Sensorless and Predictive Control, Data Driven control and Monitoring.

4. Power Electronics and Energy Conversion.

Power Electronics Modelling, Simulation, Design, Control, DC/DC Conversion, AC/AC Converters, Rectifiers, Inverters, PWM Systems.

5. Renewable Electric Energy Conversion, Processing and Storage.

Wind Energy, Photovoltaics, Hydro-Power, Battery Technologies, Fuel Cells, Energy Storage Technologies.

6. *Mechatronics and Robotics.*
 Mechatronics, Robotics, Human-Machine Interface Technology, Control of Linear and Non-linear Systems, Adaptive, Robust and Variable Structure Control.
7. *Factory Automation and Industrial Informatics.*
 Remote Sensing, Process Automation, Flexible Manufacturing Systems, Industrial Agents, Factory Automation, Safety and Reliability.
8. *Electronic Systems-on-Chip & Embedded Systems.*
 Microelectronics, HDL or High Level Language Hardware Design, System-on-chip Design, FPGAs, Embedded Systems.
9. *Computational Intelligence. Image Processing.*
 Neural Networks, Fuzzy Logic, Genetic Algorithms, Image Processing.
10. *Sensors, Actuators and Micro-/Nanotechnology.*
 Sensors, Signal/Audio/Video Applications, Networking Applications, Communication Systems, Measurements & Data Acquisition, Nanoelectronics, MEMs.
11. *Automotive Technology.*
 Electric Propulsion, Automotive Applications, Electric and Hybrid Electric Vehicles.
12. *Building Automation, Control and Management.*
 Intelligent Environment, Building Management, Building Automation.
13. *Engineering Education.*
 Educational Tools, Continuous Learning, Educational Materials and Methods, Distance Learning, Information and Communication Technologies in Laboratories, University-Industry Collaboration.
14. *Industrial Cyber-Physical Systems.*
 Digitalization of industrial systems and processes; industrial cyber-physical systems (ICPS); industrial internet-of-things (IIOT); industrial internet-of-services (IoS); CPS in industry 4.0; CPS architectures and service; ICPS and humans in the loop; ICPS complex system engineering; ICPS system of systems; applications of CPS; CPS and cyber-security; CPS modeling and analysis; large scale ICPS infrastructures; CPS scalability and complexity management; CPS validation and verification; collaborative ICPS systems; ICPS education and training; ICPS ethics.

ICIT

1. *Control Systems, Robotics and Mechatronics*
 Advanced control techniques, nonlinear and adaptive control, optimal and robust control, estimation and identification techniques, intelligent control, complex systems control, networked control, industrial control applications (e.g. smart grids, renewable energy systems, automotive, aerospace, shipping, biological systems, biomedical engineering, micro/nano systems), Mechatronics systems, robotics, autonomous mobile robots, telerobotics and teleoperation, humanoid robots, multi-robot systems, intelligent transportation, distributed collaborative systems, security & safety applications, human-robot interface, vision-based robots.
2. *Electrical Machines and Drives*
 Special machines and actuators, multiphase motors, AC motor drives control and applications, observers and sensorless methods, electrical machine design and modeling, thermal, noise and vibration issues in electrical machines, reliability, testing and diagnostics, fault detection in machines and drives, motion control, special application of machines and drives, HVAC, advanced traction control of electric vehicles and electric trains, electrical drives for ships and for aerospace. Advanced techniques in real and off line simulation of industrial drives power system and electromechanical devices.
3. *Power Electronics and Renewable Energy Conversion*
 Power converters, power electronic devices, SiC Mosfet & SiC JFET technologies, modulation techniques, integrated power electronics, modeling, simulation and control of power electronics, DC-

DC, DC-AC, AC-DC conversion, AC/AC matrix converters, multilevel converters, fault tolerant converters, high frequency links, soft switching techniques, active rectifiers, inverters, UPS, energy efficiency and storage, power electronics for smart grid, EMI and EMC issues. Wind, solar, and wave energy converters, nano, pico and micro-hydro power generators, integrated renewable systems, hybrid electric vehicles, fuel cells, advanced batteries, energy storage devices and systems, offshore underwater converters, electric transportation, energy harvesting.

4. *Power Systems and Smart Grids*

Large and small hydro generators, energy transmission and distribution, static VAR and harmonic compensations, FACTS, active and hybrid filtering, power quality devices, power management, modeling, simulation and control of power system, grid interconnection, distributed power generation, diagnostics, smart grid technologies, intelligent control systems, multi-agent systems, global and constrained optimization, electricity market liberalization.

5. *Sensors, Actuators and Micro-Nanotechnology*

Intelligent sensors, actuators and multi-sensor fusion, micro-sensors and micro-actuators, micro-nano technology, electronic instrumentation, micro-electro-mechanical systems (MEMS), RF systems integration, integrated optics and related technologies, polymer electronics, nanotechnology, biomedical engineering, microfluidics, lab-on-chip devices and technologies, MOEMS, RF-MEMS.

6. *Cloud Computing, Big Data and Software Engineering*

Cloud computing, big data, data analysis and extraction, computer networking, communication protocols, telecommunication, algorithms, distributed systems, industrial database applications, service oriented architecture, service integration, communication standards, internetworking, mobile communication, information security and trust.

7. *Electronic Systems on Chip and Embedded Control*

Real time simulation algorithms, DSP and FPGA technologies, microprocessor and FPGA based control, real time implementation and control, VHDL applications, embedded systems, real-time distributed embedded systems, technologies for system design, electronic system on chip (SoC), design methodologies and Electronic Design Automation (EDA) tools.

8. *Signal and Image Processing and Computational Intelligence*

Computer vision, virtual reality systems, industrial vision, virtual instrumentation, image & sound processing, digital signal processing, remote sensing, multimedia applications, neural networks, fuzzy logic, genetic algorithms, industrial applications of intelligent controllers.

9. *Industrial Automation, Communication, Networking and Informatics*

Building automation, factory automation and communications, flexible manufacturing systems, industrial vision, autonomous mobile robots, electrical vehicles, intelligent transportation, industrial agents, integrated systems and processes, distributed collaborative systems, human-machine interfaces, security & safety applications, infrastructures for industrial informatics portable electronics, automation systems for power distribution, industrial applications of internet technologies, multimedia, wired and wireless communications, power line communication.

APPENDIX C: TIMELINE CHART FOR IES MAJORITY SPONSORED CONFERENCES

The detailed description of the timeline may be found in Document #7

APPROVAL / REPORTING / PUBLICITY FINANCES / LOGISTICS TECHNICAL / SOCIAL PROGRAM CONFERENCE PUBLICATIONS

SHEET 1/3

PRE-APPROVAL		PRE-CONFERENCE				
4-3.5 YEARS	3.5-3 YEARS	3 YEARS*	3-2.5 YEARS	BEFORE PREVIOUS EDITION	AT PREVIOUS EDITION	≥ 1 YEAR***
Contact IES	Submit bid	Sign Operating Agreement	Register conference with IEEE	Update committees if required**	Distribute Call for Papers	Look for Special Sessions
Submit Expression of Interest			Sign sponsors MoU	Prepare Call for Papers	Make presentation	Look for keynote speakers
			Submit budget and committee list to IEEE		Conference web live	Look for external partners
			Selected volunteers take compliance classes			Bank account open
			Check if additional insurance coverage is required			Submit tax compliance to IEEE
			Sign MoU with third party for management			Submit Principles of Business Conduct Compliance Certificate and Conflict of Interest Disclosure Statement
			Send venue / hotel contract to IEEE for review and approval			Review and renegotiate hotel contract
			Apply for IEEE Publication Program			
			Register for PDF eXpress			
			Contact local IEEE Section & IES chapter			

* From conference approval to closing, progress reports must be submitted to IES C-C / AdCom twice a year

** Report to IES C-C / AdCom for approval and notify IEEE

*** IEEE may request some of these items before this milestone

APPROVAL / REPORTING / PUBLICITY FINANCES / LOGISTICS TECHNICAL / SOCIAL PROGRAM CONFERENCE PUBLICATIONS

PRE-CONFERENCE					
≥ 6 MONTHS	1 MONTH BEFORE SUBMISSION DEADLINE	4.5 MONTHS	1 WEEK BEFORE NOTIFICATION DEADLINE	2.5 MONTHS	2 MONTHS
Start activity in social networks	Deadline for Special Session proposals	Submission deadline	Complete review process	Authors' notification deadline	Review and renegotiate hotel contract
Open paper submission system	Send email announcements to IES authors' database and IEEE eNotice*	Request hotel to start submitting weekly room block reports	Make decisions on papers	Send decision letters	Post preliminary conference schedule
Launch review process				Start working on program with IES-PCT	Register for CrossCheck
Set up and test registration system				Deadline for tutorial proposals	
Publish ad in IE Magazine				Start arrangements for IES meetings	

* Within 1 week before submission deadline, send reminder emails. Announce deadline extension (2-3 weeks) if necessary

PRE-CONFERENCE				AT CONFERENCE
≥ 1.5 MONTHS	1 MONTH	1 WEEK	1-2 DAYS	CONFERENCE DAYS
Final submission and early registration deadline	Submit pre-conference forecast	Generate conference materials	Set up registration area	Monitor app and online materials
Finalize and post final program		Conference app operational and available for download	Have materials for attendees ready	Registration services
Start inviting Session Chairs		Organize / confirm logistics	Set up exhibit, information, and office areas	Post room sheets
Notify CrossCheck issues to affected authors				Distribute and collect session checklists
				Contact no-show authors
				On-site report

APPROVAL / REPORTING / PUBLICITY FINANCES / LOGISTICS TECHNICAL / SOCIAL PROGRAM CONFERENCE PUBLICATIONS

POST-CONFERENCE			
1 WEEK	1 MONTH	WITHIN 6 MONTHS	1 YEAR
Submit IEEE Xplore® package	Submit post-conference budget forecast	Submit final report to IES AdCom	Conference may be eligible to nominate candidates for IES Best Conference Paper Award and IES Best Student Paper Award
Submit list of participants	Complete all pending financial transactions	Submit 1099 / 1042 and W-8 / W-9 forms	
Submit post-conference news		Transfer surplus	
		Submit CB Destroy Check form	
		Close bank account and submit proof of closure	
		Submit payments report	
		Conduct audit	
		Submit final financial report and Certification of Accuracy	

APPENDIX D: POST CONFERENCE SURVEY FOR IECON, ISIE, AND ICIT PARTICIPANTS

- 1) Please rate the following aspects (1 lowest rating, 5 highest rating):
 - Technical content of the conference
 - Web submission system for papers (separate from conference website)
 - Review process (speed, quality of reviewer comments, ...) if you were an author or co-author
 - Conference venue facilities (rooms, audiovisuals, etc.)
 - Social acts
 - Food (lunches, coffee breaks,...)
 - Communication with conference organizers (email, social media, etc.)
 - Conference registration fee
- 2) Please indicate your registration type.
- 3) Please provide your opinion on the conference in general or in particular aspects:
 - What did you like?
 - What did you not like?
 - Other comments and suggestions
- 4) If you would like us to contact you regarding this survey, please provide your contact data (optional)